method for reducing the palladium concentration in the etching bath by cathodic electrolysis.

[Claim 3]

A resin plating method comprising:

an etching step in which an article comprising a resin material is used as an object to be treated and is subjected to etching using an acidic etching bath containing manganese;

a catalyst application step using palladium as a catalyst metal; and

an electroless plating step,

the method further comprising a step of maintaining the palladium concentration in the acidic etching bath at 100 mg/L or less,

wherein the step of maintaining the palladium concentration in the acidic etching bath at 100 mg/L or less is performed by a method for reducing the palladium concentration by iodide addition to the etching bath.

[Claim 4]

The resin plating method according to claim 2, wherein the method for reducing the palladium concentration in an etching bath by cathodic electrolysis is a method of depositing palladium in an etching bath on a cathode as metallic palladium by electrolytic treatment.

[Claim 5]

The resin plating method according to claim 3, wherein the method for reducing the palladium concentration by iodide addition to an etching bath is a method comprising adding to an etching bath at least one iodide selected from the group consisting of sodium iodide, potassium iodide, iodic acid, iodates, periodic acid, and periodates, and separating the formed precipitate.

[Claim 6]

A method for controlling a resin plating etching bath, comprising maintaining the palladium concentration in a